

74HC244; 74HCT244

Octal buffer/line driver; 3-state

Rev. 4 — 24 September 2012

1. General description

The 74HC244; 74HCT244 is an 8-bit buffer/line driver with 3-state outputs. The device can be used as two 4-bit buffers or one 8-bit buffer. The device features two output enables ($\overline{1OE}$ and $\overline{2OE}$), each controlling four of the 3-state outputs. A HIGH on $\overline{nOE}$ causes the outputs to assume a high-impedance OFF-state. Inputs include clamp diodes that enable the use of current limiting resistors to interface inputs to voltages in excess of V_{CC} .

2. Features and benefits

- Input levels:
 - ◆ For 74HC244: CMOS level
 - ◆ For 74HCT244: TTL level
- Octal bus interface
- Non-inverting 3-state outputs
- Complies with JEDEC standard no. 7 A
- ESD protection:
 - ◆ HBM JESD22-A114F exceeds 2000 V
 - ◆ MM JESD22-A115-A exceeds 200 V
- Multiple package options
- Specified from $-40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$ and $-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$

3. Ordering information

Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
74HC244N 74HCT244N	$-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$	DIP20	plastic dual in-line package; 20 leads (300 mil)	SOT146-1
74HC244D 74HCT244D	$-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$	SO20	plastic small outline package; 20 leads; body width 7.5 mm	SOT163-1
74HC244DB 74HCT244DB	$-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$	SSOP20	plastic shrink small outline package; 20 leads; body width 5.3 mm	SOT339-1
74HC244PW 74HCT244PW	$-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$	TSSOP20	plastic thin shrink small outline package; 20 leads; body width 4.4 mm	SOT360-1
74HC244BQ 74HCT244BQ	$-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$	DHVQFN20	plastic dual-in-line compatible thermal enhanced very thin quad flat package; no leads; 20 terminals; body $2.5 \times 4.5 \times 0.85\text{ mm}$	SOT764-1

4. Functional diagram

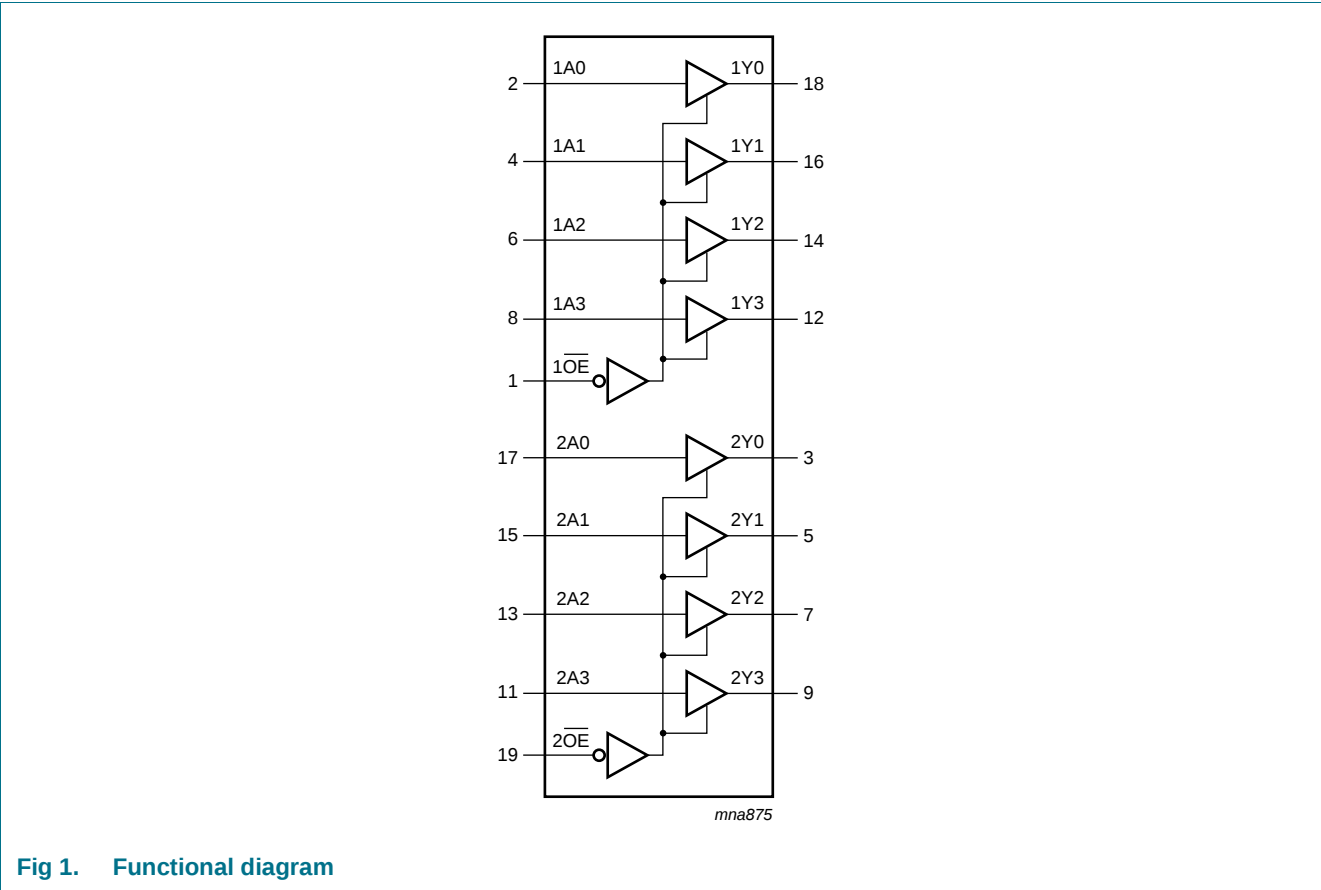


Fig 1. Functional diagram

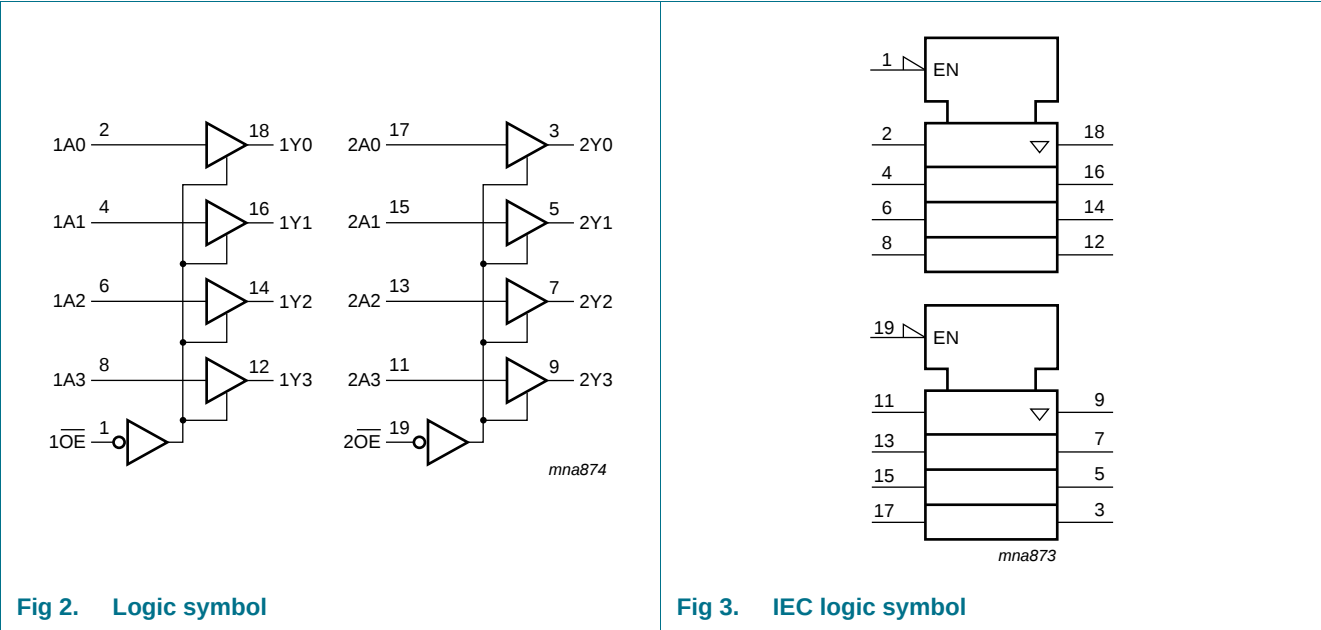


Fig 2. Logic symbol

Fig 3. IEC logic symbol

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5. Pinning information

5.1 Pinning

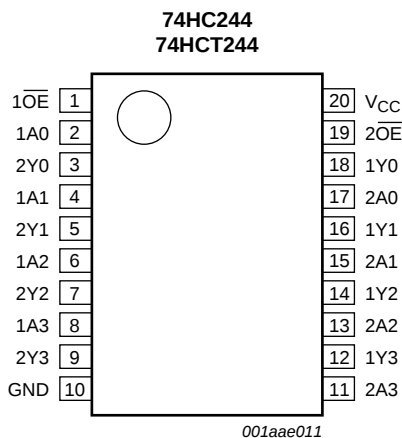
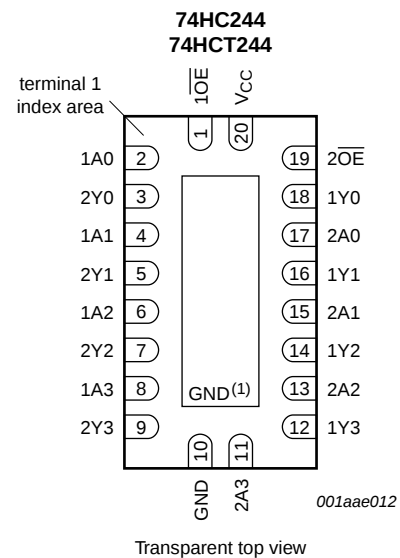


Fig 4. Pin configuration DIP20, SO20, (T)SSOP20



- (1) This is not a supply pin. The substrate is attached to this pad using conductive die attach material. There is no electrical or mechanical requirement to solder this pad. However, if it is soldered, the solder land should remain floating or be connected to GND.

Fig 5. Pin configuration DHVQFN20

5.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
$\overline{1OE}$, $\overline{2OE}$	1, 19	output enable input (active LOW)
1A0, 1A1, 1A2, 1A3	2, 4, 6, 8	data input
2Y0, 2Y1, 2Y2, 2Y3	3, 5, 7, 9	bus output
GND	10	ground (0 V)
2A0, 2A1, 2A2, 2A3	17, 15, 13, 11	data input
1Y0, 1Y1, 1Y2, 1Y3	18, 16, 14, 12	bus output
V _{CC}	20	supply voltage

6. Functional description

Table 3. Function table^[1]

Input		Output
nOE	nAn	nYn
L	L	L
L	H	H
H	X	Z

[1] H = HIGH voltage level; L = LOW voltage level; X = don't care; Z = high-impedance OFF-state.

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
V _{CC}	supply voltage		-0.5	+7	V
I _{IK}	input clamping current	V _I < -0.5 V or V _I > V _{CC} + 0.5 V	-	±20	mA
I _{OK}	output clamping current	V _O < -0.5 V or V _O > V _{CC} + 0.5 V	-	±20	mA
I _O	output current	-0.5 V < V _O < V _{CC} + 0.5 V	-	±35	mA
I _{CC}	supply current		-	70	mA
I _{GND}	ground current		-70	-	mA
T _{stg}	storage temperature		-65	+150	°C
P _{tot}	total power dissipation	DIP20 package	^[1] -	750	mW
		SO20, SSOP20, TSSOP20 and DHVQFN20 packages	^[2] -	500	mW

[1] For DIP20 package: P_{tot} derates linearly with 12 mW/K above 70 °C.

[2] For SO20 packages: P_{tot} derates linearly with 8 mW/K above 70 °C.

For SSOP20 and TSSOP20 packages: P_{tot} derates linearly with 5.5 mW/K above 60 °C.

For DHVQFN20 packages: above 60 °C, P_{tot} derates linearly with 4.5 mW/K.

8. Recommended operating conditions

Table 5. Recommended operating conditions

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
74HC244						
V _{CC}	supply voltage		2.0	5.0	6.0	V
V _I	input voltage		0	-	V _{CC}	V
V _O	output voltage		0	-	V _{CC}	V
Δt/ΔV	input transition rise and fall rate	V _{CC} = 2.0 V	-	-	625	ns/V
		V _{CC} = 4.5 V	-	1.67	139	ns/V
		V _{CC} = 6.0 V	-	-	83	ns/V
T _{amb}	ambient temperature		-40	-	+125	°C

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Table 5. Recommended operating conditions ...continued

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
74HCT244						
V_{CC}	supply voltage		4.5	5.0	5.5	V
V_I	input voltage		0	-	V_{CC}	V
V_O	output voltage		0	-	V_{CC}	V
$\Delta t/\Delta V$	input transition rise and fall rate	$V_{CC} = 4.5\text{ V}$	-	1.67	139	ns/V
T_{amb}	ambient temperature		-40	-	+125	°C

9. Static characteristics

Table 6. Static characteristics

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	25 °C			−40 °C to +85 °C		−40 °C to +125 °C		Unit	
			Min	Typ	Max	Min	Max	Min	Max		
74HC244											
V _{IH}	HIGH-level input voltage	V _{CC} = 2.0 V	1.5	1.2	-	1.5	-	1.5	-	V	
		V _{CC} = 4.5 V	3.15	2.4	-	3.15	-	3.15	-	V	
		V _{CC} = 6.0 V	4.2	3.2	-	4.2	-	4.2	-	V	
V _{IL}	LOW-level input voltage	V _{CC} = 2.0 V	-	0.8	0.5	-	0.5	-	0.5	V	
		V _{CC} = 4.5 V	-	2.1	1.35	-	1.35	-	1.35	V	
		V _{CC} = 6.0 V	-	2.8	1.8	-	1.8	-	1.8	V	
V _{OH}	HIGH-level output voltage	V _I = V _{IH} or V _{IL}									
		I _O = −20 μA; V _{CC} = 2.0 V	1.9	2.0	-	1.9	-	1.9	-	V	
		I _O = −20 μA; V _{CC} = 4.5 V	4.4	4.5	-	4.4	-	4.4	-	V	
		I _O = −20 μA; V _{CC} = 6.0 V	5.9	6.0	-	5.9	-	5.9	-	V	
		I _O = −6.0 mA; V _{CC} = 4.5 V	3.98	4.32	-	3.84	-	3.7	-	V	
V _{OL}	LOW-level output voltage	I _O = −7.8 mA; V _{CC} = 6.0 V	5.48	5.81	-	5.34	-	5.2	-	V	
		V _I = V _{IH} or V _{IL}									
		I _O = 20 μA; V _{CC} = 2.0 V	-	0	0.1	-	0.1	-	0.1	V	
		I _O = 20 μA; V _{CC} = 4.5 V	-	0	0.1	-	0.1	-	0.1	V	
		I _O = 20 μA; V _{CC} = 6.0 V	-	0	0.1	-	0.1	-	0.1	V	
		I _O = 6.0 mA; V _{CC} = 4.5 V	-	0.15	0.26	-	0.33	-	0.4	V	
I _I	input leakage current	I _O = 7.8 mA; V _{CC} = 6.0 V	-	0.16	0.26	-	0.33	-	0.4	V	
		V _I = V _{CC} or GND; V _{CC} = 6.0 V	-	-	±0.1	-	±1.0	-	±1.0	μA	
		per input pin; V _I = V _{IH} or V _{IL} ; V _O = V _{CC} or GND; other inputs at V _{CC} or GND; V _{CC} = 6.0 V; I _O = 0 A	-	-	±0.5	-	±5.0	-	±10	μA	
		supply current	V _I = V _{CC} or GND; I _O = 0 A; V _{CC} = 6.0 V	-	-	8.0	-	80	-	160	μA
		input capacitance		-	3.5	-	-	-	-	-	pF

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Table 6. Static characteristics ...continued

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	25 °C			–40 °C to +85 °C		–40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
74HCT244										
V _{IH}	HIGH-level input voltage	V _{CC} = 4.5 V to 5.5 V	2.0	1.6	-	2.0	-	2.0	-	V
V _{IL}	LOW-level input voltage	V _{CC} = 4.5 V to 5.5 V	-	1.2	0.8	-	0.8	-	0.8	V
V _{OH}	HIGH-level output voltage	V _I = V _{IH} or V _{IL} ; V _{CC} = 4.5 V								
		I _O = –20 µA	4.4	4.5	-	4.4	-	4.4	-	V
		I _O = –6 mA	3.98	4.32	-	3.84	-	3.7	-	V
V _{OL}	LOW-level output voltage	V _I = V _{IH} or V _{IL} ; V _{CC} = 4.5 V								
		I _O = 20 µA	-	0	0.1	-	0.1	-	0.1	V
		I _O = 6.0 mA	-	0.16	0.26	-	0.33	-	0.4	V
I _I	input leakage current	V _I = V _{CC} or GND; V _{CC} = 5.5 V	-	-	±0.1	-	±1.0	-	±1.0	µA
I _{OZ}	OFF-state output current	per input pin; V _I = V _{IH} or V _{IL} ; V _O = V _{CC} or GND; other inputs at V _{CC} or GND; V _{CC} = 5.5 V; I _O = 0 A	-	-	±0.5	-	±5.0	-	±10	µA
I _{CC}	supply current	V _I = V _{CC} or GND; V _{CC} = 5.5 V; I _O = 0 A	-	-	8.0	-	80	-	160	µA
ΔI _{CC}	additional supply current	per input pin; V _I = V _{CC} – 2.1 V; other inputs at V _{CC} or GND; V _{CC} = 4.5 V to 5.5 V; I _O = 0 A	-	70	252	-	315	-	343	µA
C _I	input capacitance		-	3.5	-	-	-	-	-	pF

10. Dynamic characteristics

Table 7. Dynamic characteristics

GND = 0 V; for load circuit see [Figure 8](#).

Symbol	Parameter	Conditions	25 °C			–40 °C to +125 °C		Unit
			Min	Typ	Max	Max (85 °C)	Max (125 °C)	

74HC244

t _{pd}	propagation delay	nAn to nYn; see Figure 6						
		V _{CC} = 2.0 V	-	30	110	145	165	ns
		V _{CC} = 4.5 V	-	11	22	28	33	ns
		V _{CC} = 5.0 V; C _L = 15 pF	-	9	-	-	-	ns
		V _{CC} = 6.0 V	-	9	19	24	28	ns

74HC244; 74HCT244

Octal buffer/line driver; 3-state

Table 7. Dynamic characteristics ...continued

$GND = 0\text{ V}$; for load circuit see [Figure 8](#).

Symbol	Parameter	Conditions	25 °C			–40 °C to +125 °C		Unit
			Min	Typ	Max	Max (85 °C)	Max (125 °C)	
t_{en}	enable time	$n\overline{OE}$ to nYn ; see Figure 7 [2]						
		$V_{CC} = 2.0\text{ V}$	-	36	150	190	225	ns
		$V_{CC} = 4.5\text{ V}$	-	13	30	38	45	ns
		$V_{CC} = 6.0\text{ V}$	-	10	26	33	38	ns
t_{dis}	disable time	$n\overline{OE}$ to nYn or see Figure 7 [3]						
		$V_{CC} = 2.0\text{ V}$	-	39	150	190	225	ns
		$V_{CC} = 4.5\text{ V}$	-	14	30	38	45	ns
		$V_{CC} = 6.0\text{ V}$	-	11	26	33	38	ns
t_t	transition time	see Figure 6 [4]						
		$V_{CC} = 2.0\text{ V}$	-	14	60	75	90	ns
		$V_{CC} = 4.5\text{ V}$	-	5	12	15	18	ns
		$V_{CC} = 6.0\text{ V}$	-	4	10	13	15	ns
C_{PD}	power dissipation capacitance	per buffer; $V_I = GND$ to V_{CC} [5]	-	35	-	-	-	pF

74HCT244

t_{pd}	propagation delay	nAn to nYn ; see Figure 6 [1]						
		$V_{CC} = 4.5\text{ V}$	-	13	22	28	33	ns
		$V_{CC} = 5.0\text{ V}$; $C_L = 15\text{ pF}$	-	11	-	-	-	ns
t_{en}	enable time	$n\overline{OE}$ to nYn ; $V_{CC} = 4.5\text{ V}$; see Figure 7 [2]	-	15	30	38	45	ns
t_{dis}	disable time	$n\overline{OE}$ to nYn ; $V_{CC} = 4.5\text{ V}$; see Figure 7 [3]	-	15	25	31	38	ns
t_t	transition time	$V_{CC} = 4.5\text{ V}$; see Figure 6 [4]	-	5	12	15	18	ns
C_{PD}	power dissipation capacitance	per buffer; $V_I = GND$ to $V_{CC} - 1.5\text{ V}$ [5]	-	35	-	-	-	pF

[1] t_{pd} is the same as t_{PHL} and t_{PLH} .

[2] t_{en} is the same as t_{PZH} and t_{PZL} .

[3] t_{dis} is the same as t_{PHZ} and t_{PLZ} .

[4] t_t is the same as t_{THL} and t_{TLH} .

[5] C_{PD} is used to determine the dynamic power dissipation (P_D in μW):

$$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \sum (C_L \times V_{CC}^2 \times f_o) \text{ where:}$$

f_i = input frequency in MHz;

f_o = output frequency in MHz;

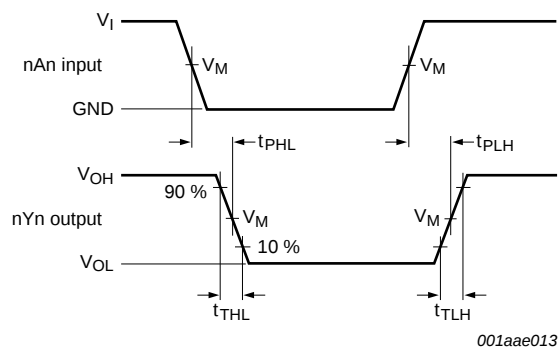
C_L = output load capacitance in pF;

V_{CC} = supply voltage in V;

N = number of inputs switching;

$\sum (C_L \times V_{CC}^2 \times f_o)$ = sum of outputs.

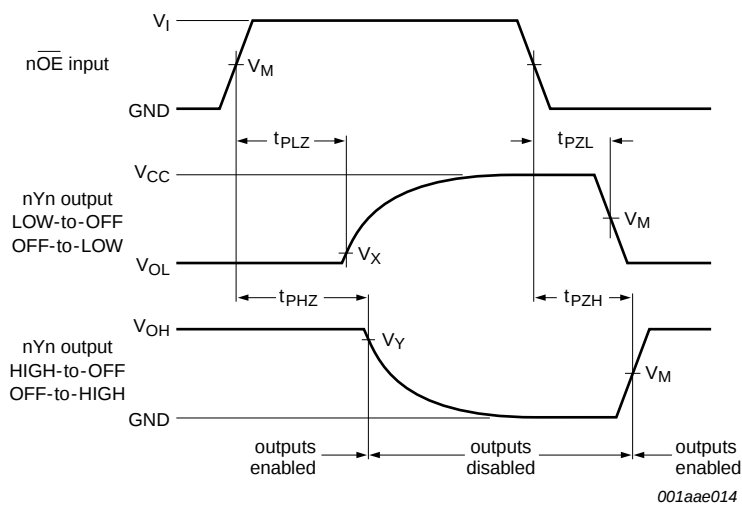
11. Waveforms



Measurement points are given in [Table 8](#).

V_{OL} and V_{OH} are typical voltage output levels that occur with the output load.

Fig 6. Input (nAn) to output (nYn) propagation delays and output transition times



Measurement points are given in [Table 8](#).

V_{OL} and V_{OH} are typical voltage output levels that occur with the output load.

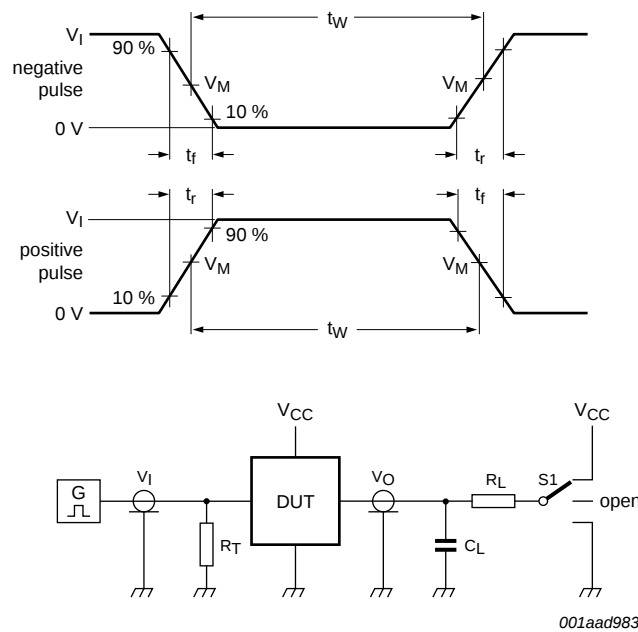
Fig 7. 3-state enable and disable times

Table 8. Measurement points

Type	Input	Output		
	V_M	V_M	V_X	V_Y
74HC244	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$	$0.1 \times V_{CC}$	$0.9 \times V_{CC}$
74HCT244	1.3 V	1.3 V	$0.1 \times V_{CC}$	$0.9 \times V_{CC}$

74HC244; 74HCT244

Octal buffer/line driver; 3-state



Test data is given in [Table 9](#).

Definitions test circuit:

R_T = Termination resistance should be equal to output impedance Z_o of the pulse generator.

C_L = Load capacitance including jig and probe capacitance.

R_L = Load resistance.

S1 = Test selection switch.

Fig 8. Test circuit for measuring switching times

Table 9. Test data

Type	Input		Load		S1 position		
	V_I	t_r, t_f	C_L	R_L	t_{PHL}, t_{PLH}	t_{PZH}, t_{PHZ}	t_{PZL}, t_{PLZ}
74HC244	V_{CC}	6 ns	15 pF, 50 pF	1 k Ω	open	GND	V_{CC}
74HCT244	3 V	6 ns	15 pF, 50 pF	1 k Ω	open	GND	V_{CC}

12. Package outline

DIP20: plastic dual in-line package; 20 leads (300 mil)

SOT146-1

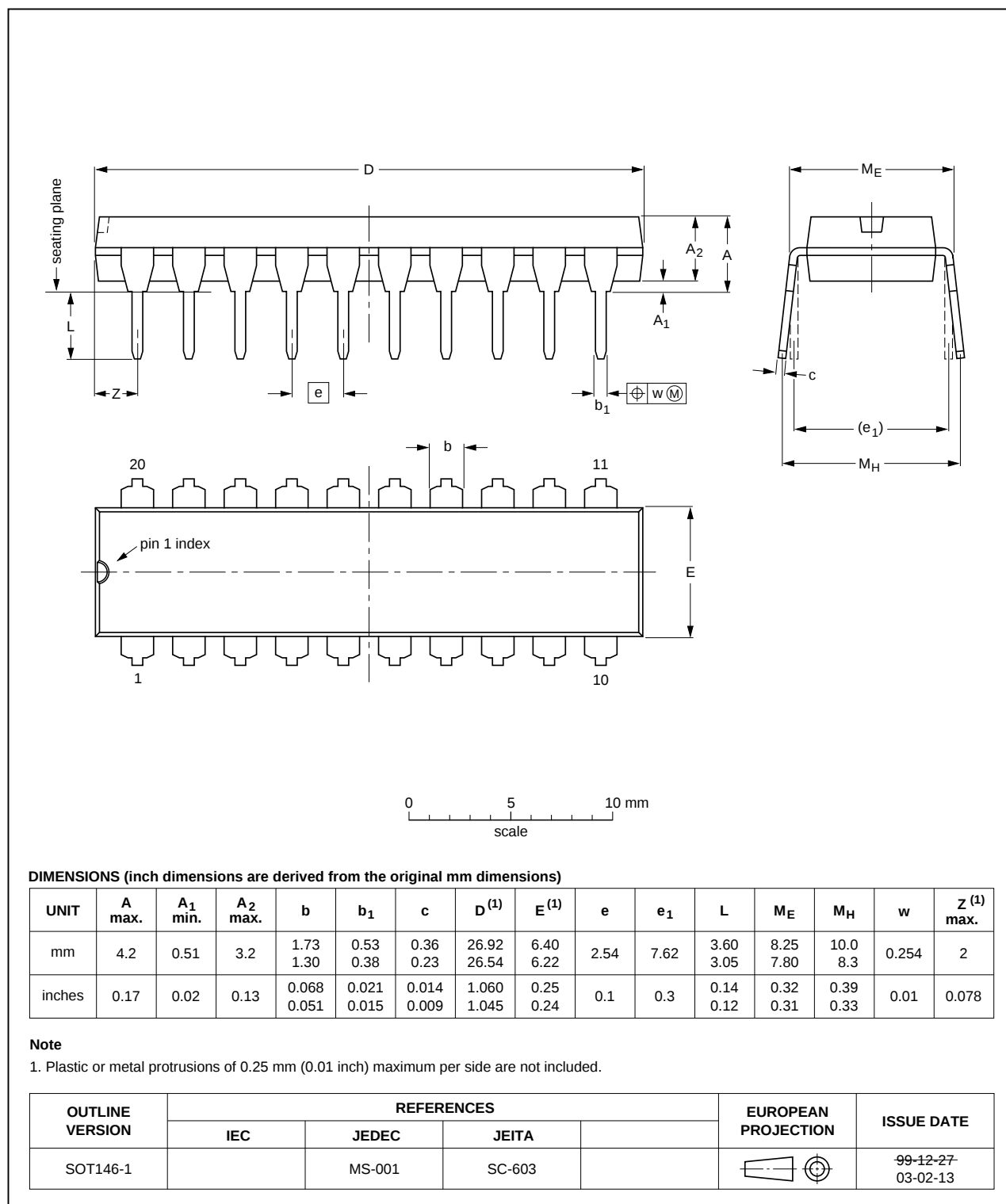


Fig 9. Package outline SOT146-1 (DIP20)

74HC244; 74HCT244

Octal buffer/line driver; 3-state

SO20: plastic small outline package; 20 leads; body width 7.5 mm

SOT163-1

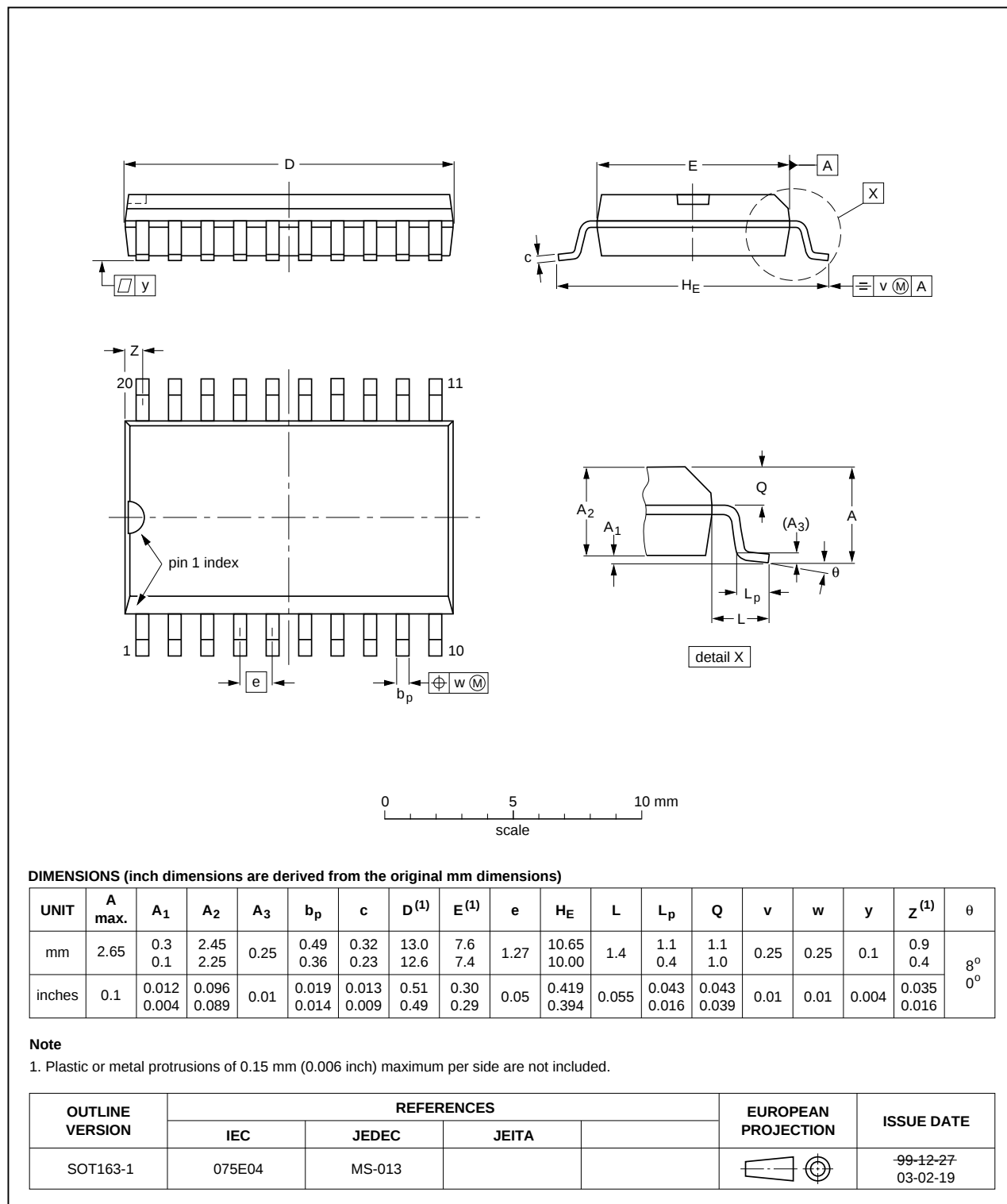


Fig 10. Package outline SOT163-1 (SO20)

74HC244; 74HCT244

Octal buffer/line driver; 3-state

SSOP20: plastic shrink small outline package; 20 leads; body width 5.3 mm

SOT339-1

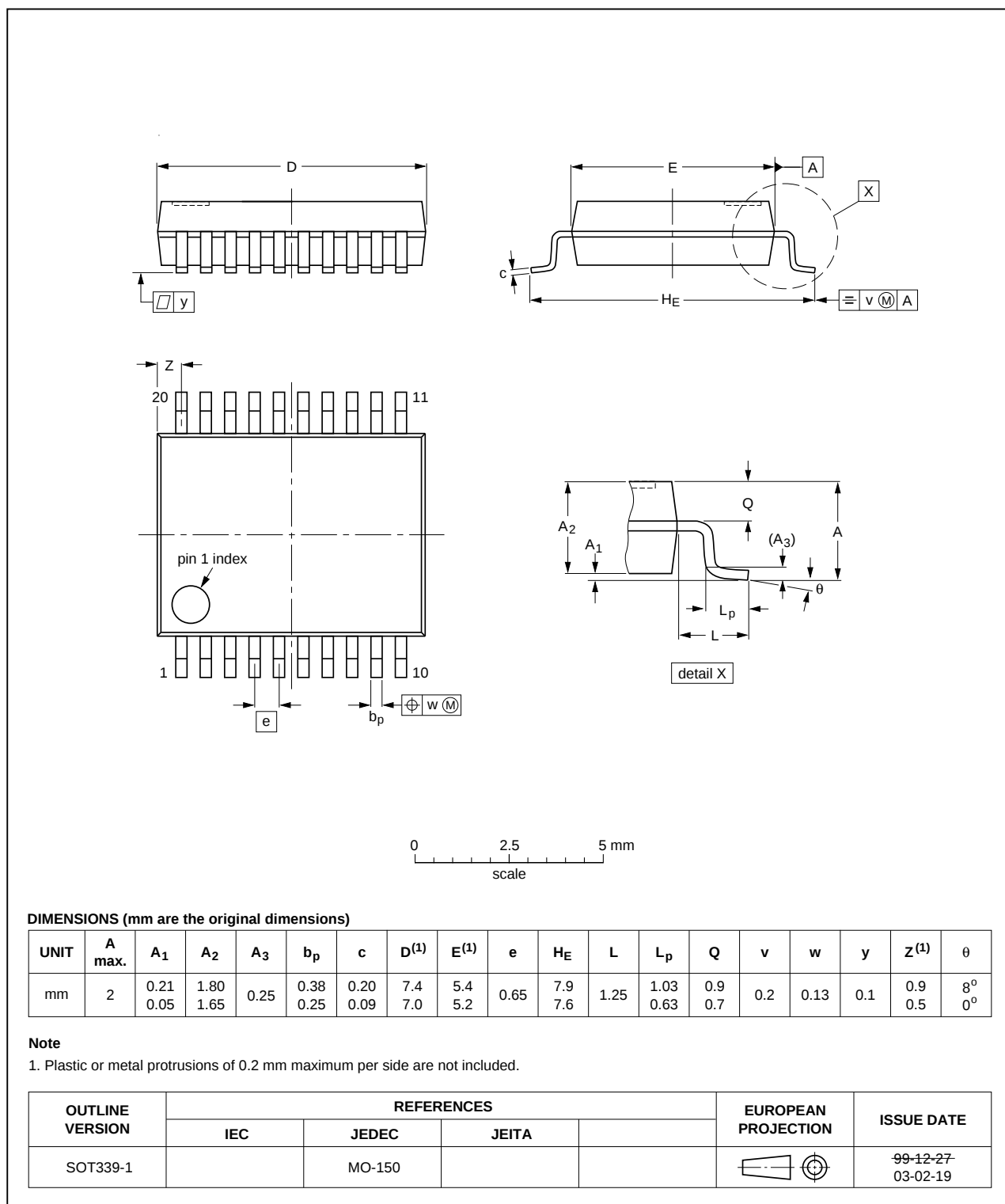


Fig 11. Package outline SOT339-1 (SSOP20)

74HC244; 74HCT244

Octal buffer/line driver; 3-state

TSSOP20: plastic thin shrink small outline package; 20 leads; body width 4.4 mm

SOT360-1

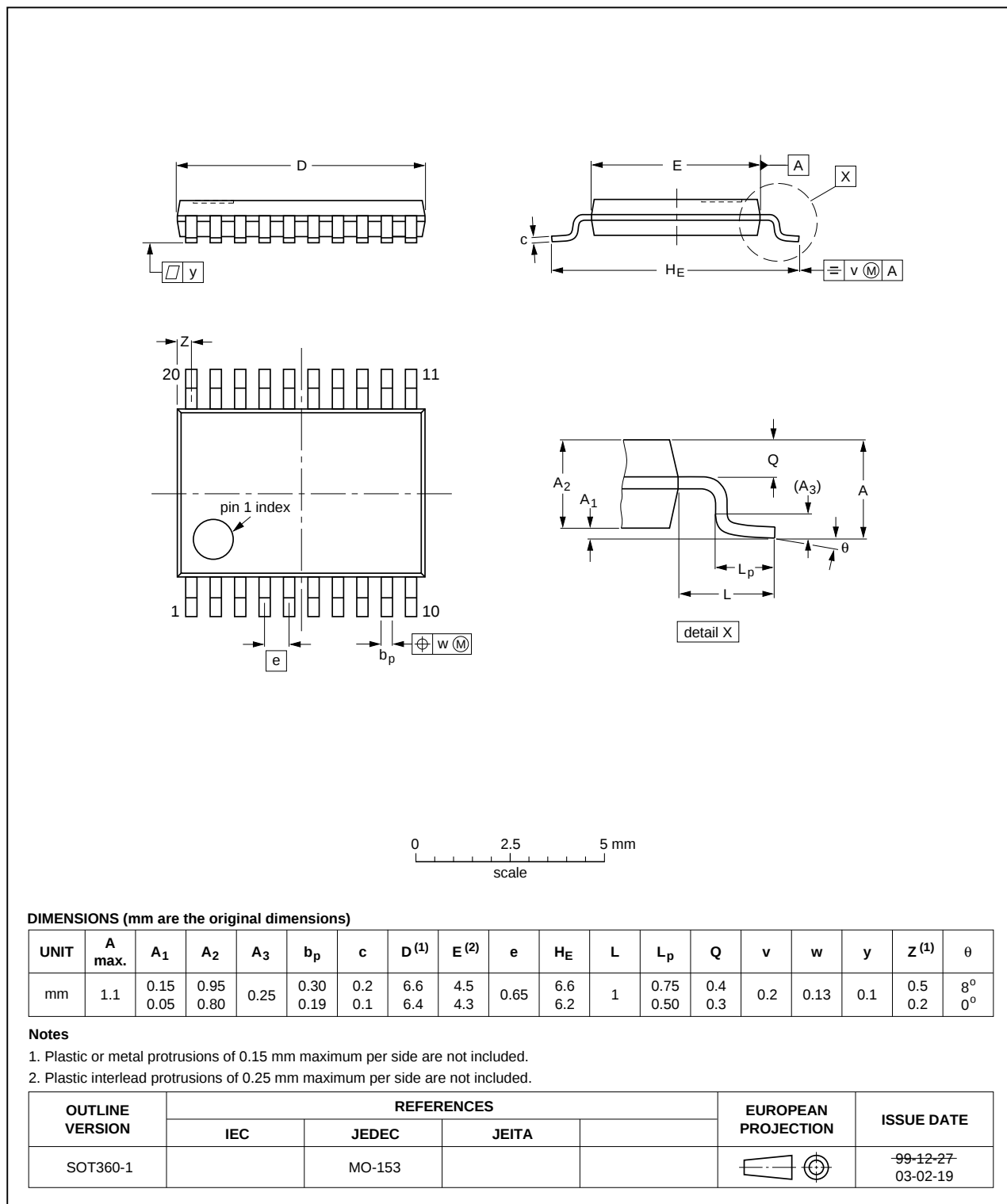


Fig 12. Package outline SOT360-1 (TSSOP20)

74HC244; 74HCT244

Octal buffer/line driver; 3-state

DHVQFN20: plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads;
20 terminals; body 2.5 x 4.5 x 0.85 mm

SOT764-1

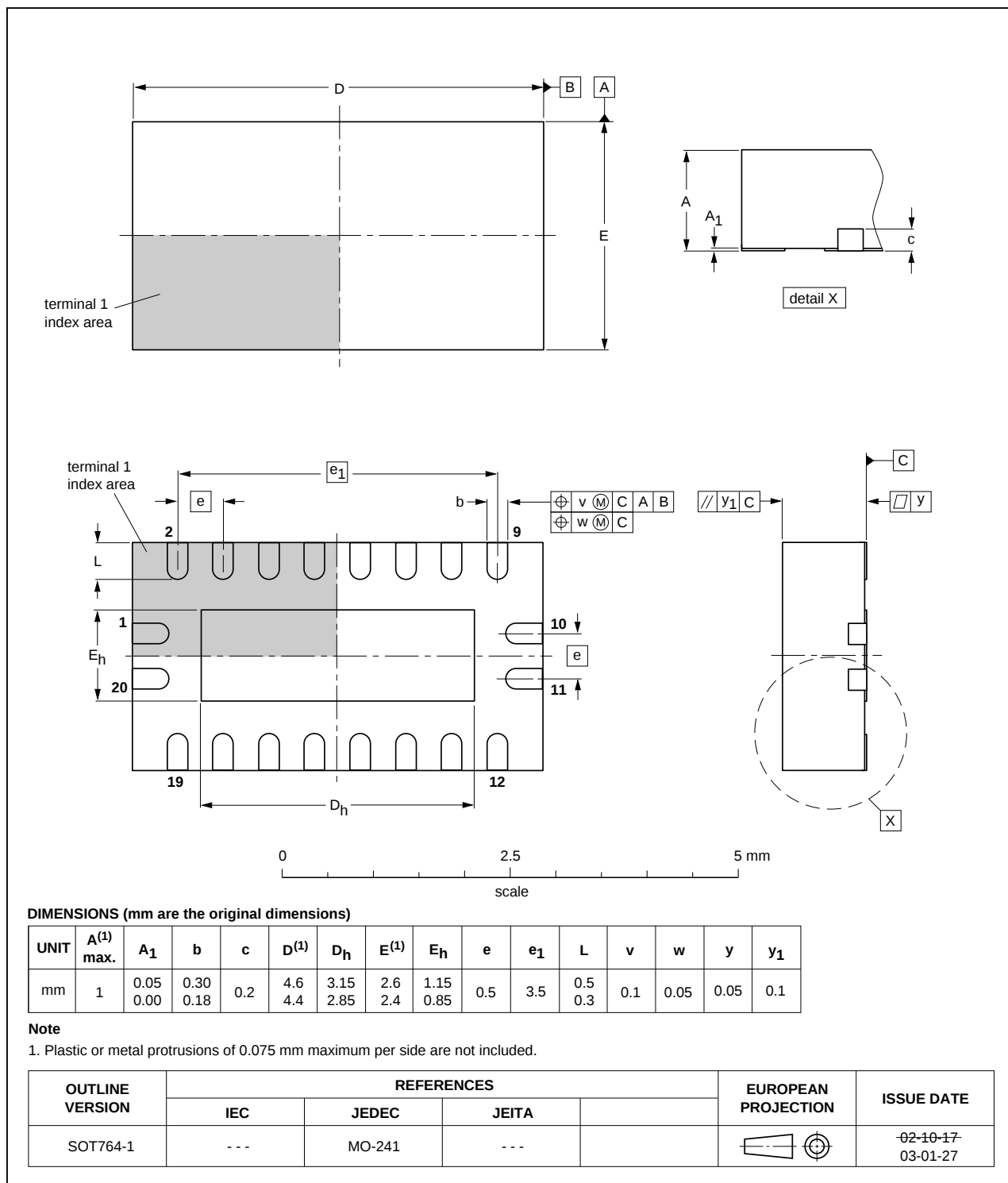


Fig 13. Package outline SOT764-1 (DHVQFN20)

13. Abbreviations

Table 10. Abbreviations

Acronym	Description
CMOS	Complementary Metal Oxide Semiconductor
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model
TTL	Transistor-Transistor Logic